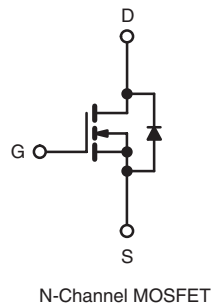
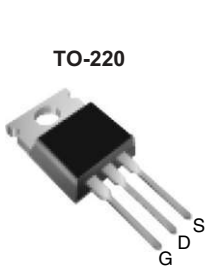


## Power MOSFET

PRODUCT SUMMARY		
$V_{DS}$ (V)	450	
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = 10$ V	1.2
$Q_g$ (Max.) (nC)	45	
$Q_{gs}$ (nC)	6.6	
$Q_{gd}$ (nC)	24	
Configuration	Single	



### FEATURES

- Dynamic  $dV/dt$  Rating
- Repetitive Avalanche Rated
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead (Pb)-free


**RoHS  
COMPLIANT**

### DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



ORDERING INFORMATION	
Package	TO-220
Lead (Pb)-free	IRF734PbF
	SiHF734-E3

ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	450	V	
Gate-Source Voltage		$V_{GS}$	$\pm 20$		
Continuous Drain Current	$V_{GS}$ at 10 V	$I_D$	$T_C = 25$ °C	4.9	A
			$T_C = 100$ °C	3.1	
Pulsed Drain Current <sup>a</sup>		$I_{DM}$	20		
Linear Derating Factor			0.59	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>		$E_{AS}$	330	mJ	
Repetitive Avalanche Current <sup>a</sup>		$I_{AR}$	4.9	A	
Repetitive Avalanche Energy <sup>a</sup>		$E_{AR}$	7.4	mJ	
Maximum Power Dissipation	$T_C = 25$ °C	$P_D$	74	W	
Peak Diode Recovery $dV/dt^c$		$dV/dt$	4.0	V/ns	
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature)	for 10 s		300 <sup>d</sup>		
Mounting Torque	6-32 or M3 screw		10	lbf · in	
			1.1	N · m	

#### Notes

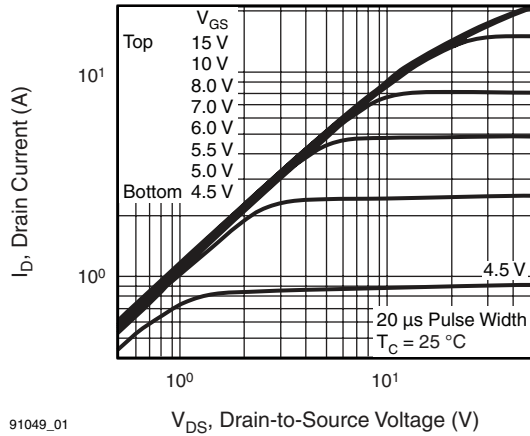
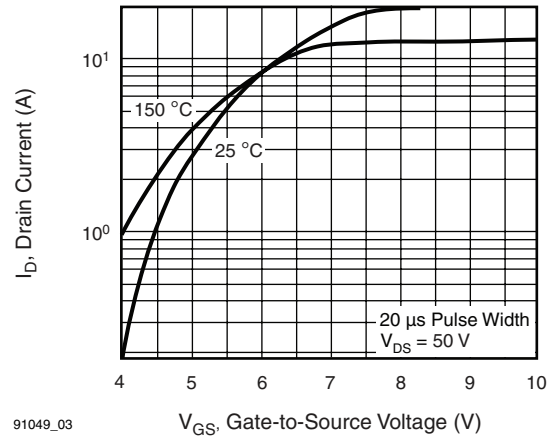
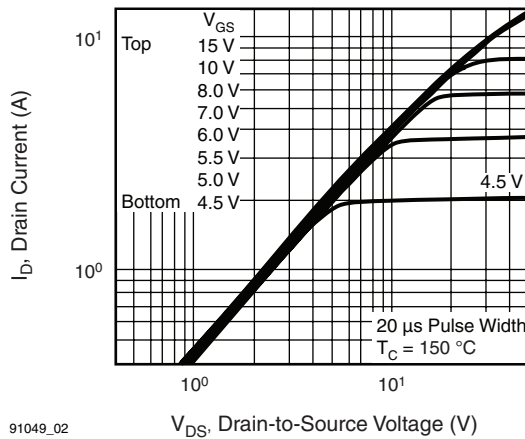
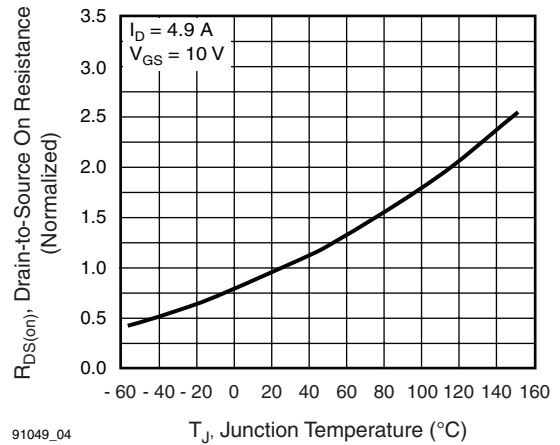
- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 50$  V, starting  $T_J = 25$  °C,  $L = 24$  mH,  $R_G = 25$   $\Omega$ ,  $I_{AS} = 4.9$  A (see fig. 12).
- $I_{SD} \leq 4.9$  A,  $dI/dt \leq 80$  A/ $\mu$ s,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150$  °C.
- 1.6 mm from case.

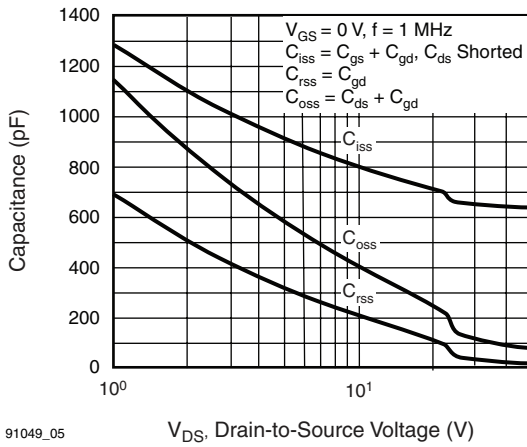
THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	62	°C/W
Case-to-Sink, Flat, Greased Surface	$R_{thCS}$	0.50	-	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	1.7	

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	450	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$ , $I_D = 1\text{ mA}$	-	0.63	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.0	-	4.0	V
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20\text{ V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 450\text{ V}, V_{GS} = 0\text{ V}$	-	-	25	$\mu\text{A}$
		$V_{DS} = 360\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 2.9\text{ A}^b$	-	-	1.2	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS} = 50\text{ V}, I_D = 2.9\text{ A}^b$	3.0	-	-	S
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V},$ $V_{DS} = 25\text{ V},$ $f = 1.0\text{ MHz}$ , see fig. 5	-	680	-	pF
Output Capacitance	$C_{oss}$		-	190	-	
Reverse Transfer Capacitance	$C_{rss}$		-	75	-	
Total Gate Charge	$Q_g$	$V_{GS} = 10\text{ V},$ $I_D = 4.9\text{ A}, V_{DS} = 360\text{ V}$ see fig. 6 and 13 <sup>b</sup>	-	-	45	nC
Gate-Source Charge	$Q_{gs}$		-	-	6.6	
Gate-Drain Charge	$Q_{gd}$		-	-	24	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 225\text{ V}, I_D = 4.9\text{ A}$ $R_G = 12\text{ }\Omega, R_D = 45\text{ }\Omega$ , see fig. 10 <sup>b</sup>	-	5.9	-	ns
Rise Time	$t_r$		-	22	-	
Turn-Off Delay Time	$t_{d(off)}$		-	40	-	
Fall Time	$t_f$		-	21	-	
Internal Drain Inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact 	-	4.5	-	nH
Internal Source Inductance	$L_S$		-	7.5	-	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	4.9	A
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$		-	-	20	
Body Diode Voltage	$V_{SD}$	$T_J = 25\text{ }^\circ\text{C}, I_S = 4.9\text{ A}, V_{GS} = 0\text{ V}^b$	-	-	2.0	V
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25\text{ }^\circ\text{C}, I_F = 4.9\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$	-	460	690	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	1.8	2.7	$\mu\text{C}$
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )				

### Notes

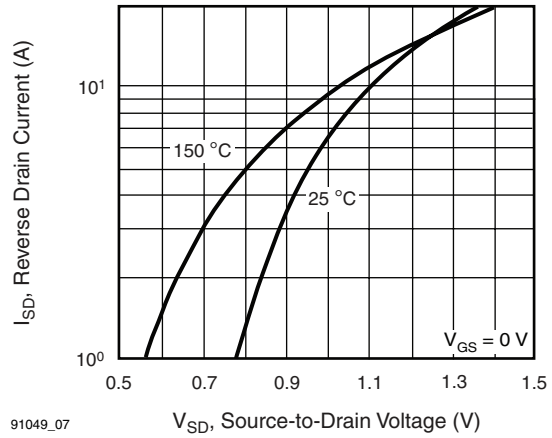
- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

**Fig. 1 - Typical Output Characteristics,  $T_C = 25\text{ }^\circ\text{C}$** 

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 2 - Typical Output Characteristics,  $T_C = 150\text{ }^\circ\text{C}$** 

**Fig. 4 - Normalized On-Resistance vs. Temperature**



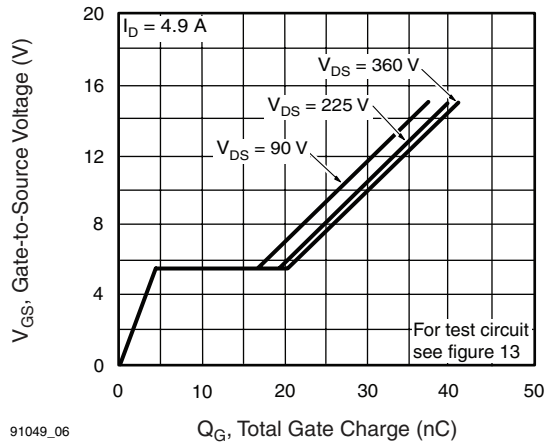
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Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



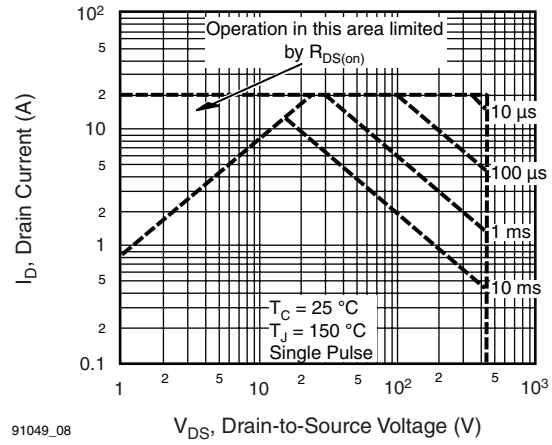
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Fig. 7 - Typical Source-Drain Diode Forward Voltage



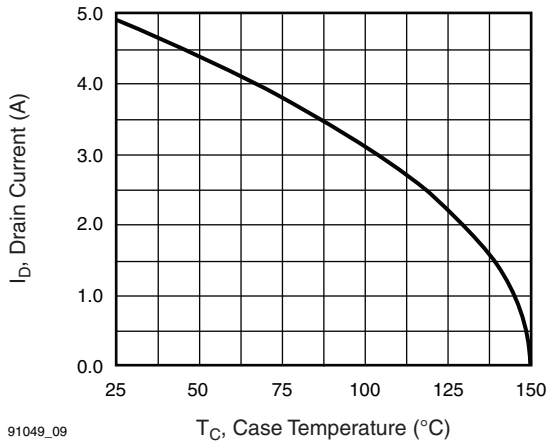
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Fig. 6 - Typical Gate Charge vs. Drain-to-Source Voltage



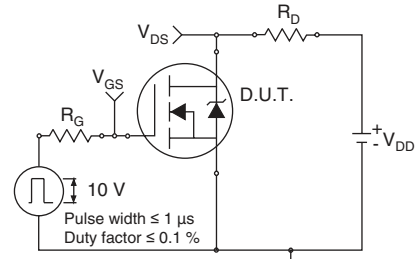
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Fig. 8 - Maximum Safe Operating Area

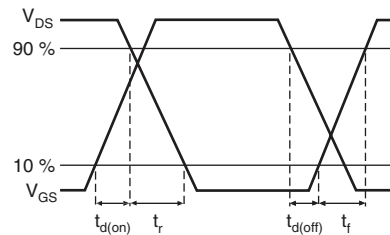


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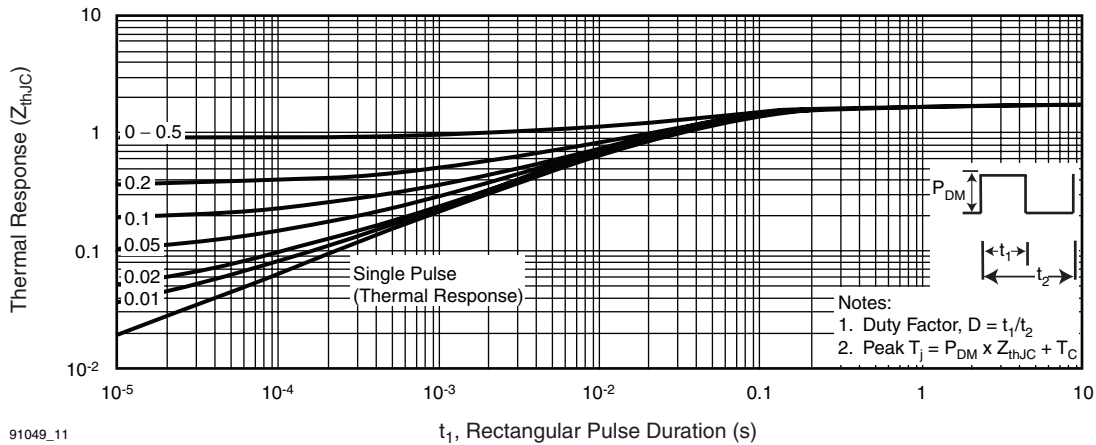
**Fig. 9 - Maximum Drain Current vs. Case Temperature**



**Fig. 10a - Switching Time Test Circuit**

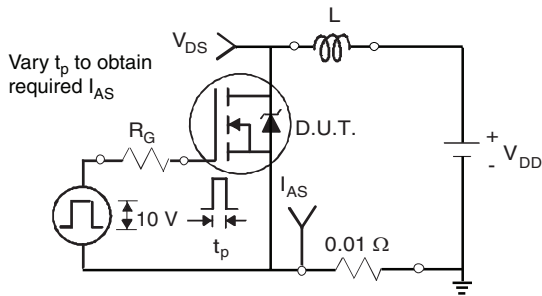


**Fig. 10b - Switching Time Waveforms**

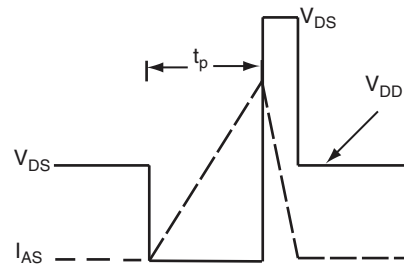


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**Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



**Fig. 12a - Unclamped Inductive Test Circuit**



**Fig. 12b - Unclamped Inductive Waveforms**

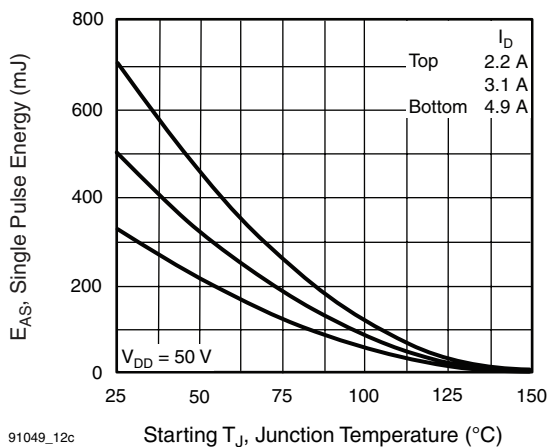


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

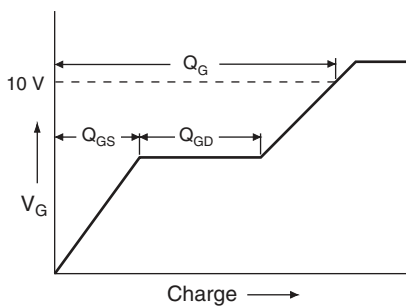


Fig. 13a - Basic Gate Charge Waveform

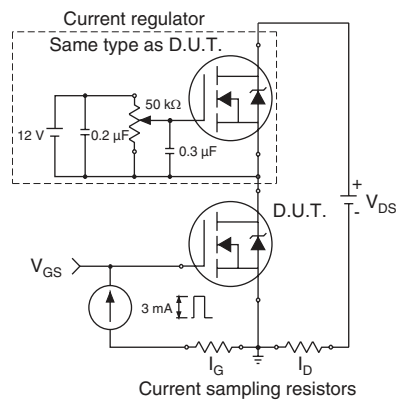
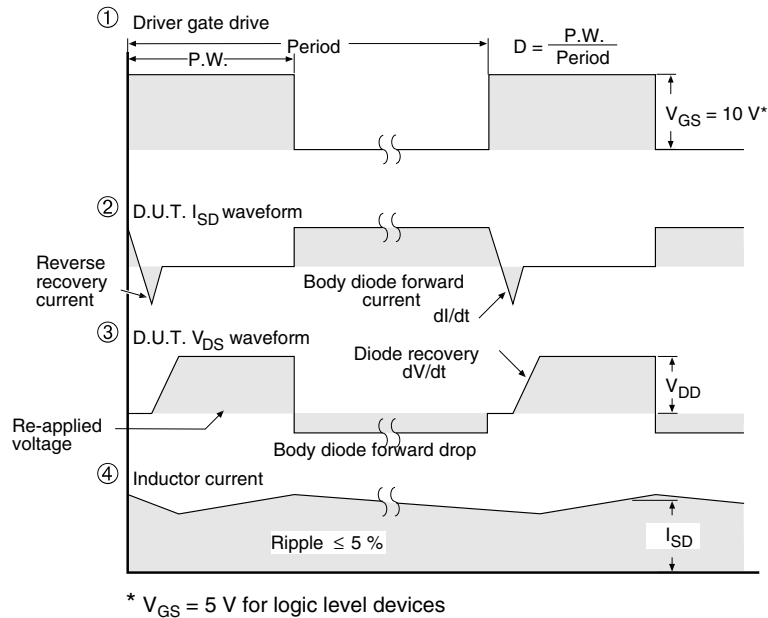


Fig. 13b - Gate Charge Test Circuit

**Peak Diode Recovery dV/dt Test Circuit**

**Fig. 14 - For N-Channel**

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